

Laminate circuit board mfr. - comprises laminating base boards
impregnated with thermosetting resin contg. inorganic filler NoAbstract
NoDwg

Patent Assignee: MATSUSHITA ELECTRIC WORKS LTD (MATW)

Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 1202442	A	19890815	JP 8826944	A	19880208	198938 B

Priority Applications (No Type Date): JP 8826944 A 19880208

Patent Details:

Patent No	Kind	Lan Pg	Main IPC	Filing Notes
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Title Terms: LAMINATE; CIRCUIT; BOARD; MANUFACTURE; COMPRISE; LAMINATE;
BASE; BOARD; IMPREGNATE; THERMOSETTING; RESIN; CONTAIN; INORGANIC; FILL;
NOABSTRACT

Derwent Class: A85; L03; P73; V04

International Patent Class (Additional): B32B-015/08; H05K-003/42

File Segment: CPI; EPI; EngPI

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